

ABSTRACT

5 A circuit package may include an upper surface of first conductive elements and second conductive elements. The first conductive elements may receive input/output signals from respective conductive elements of an integrated circuit die, and the second conductive elements may receive a first plurality of the input/output signals from respective ones of the first conductive elements. A lower surface of the package may include third conductive elements, the third conductive elements to receive a second plurality of the input/output signals from respective other ones of the first conductive elements.